512Kx32 SRAM MODULE *PRELIMINARY**

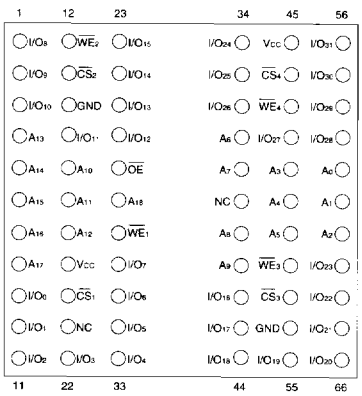
FEATURES

- Access Times of 55nS to 120nS
- Packaging
  - 66-pin, PGA Type, 1.38 inch square HIP, Hermetic Ceramic Package
  - 68 lead, 40 mm Hermetic CQFP
- Organized as 512Kx32; User Configurable as 1024Kx16 or 2Mx8.
- Battery Back-Up Operation
- Commercial, Industrial and Military Temperature Ranges
- TTL Compatible Inputs and Outputs
- 2.7V to 5.5 Volt Supply Voltage Range
- Low Power CMOS
- Built in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight
  WS512K32-XHX - 13 grams typical
  WS512K32-XG4X - 20 grams typical

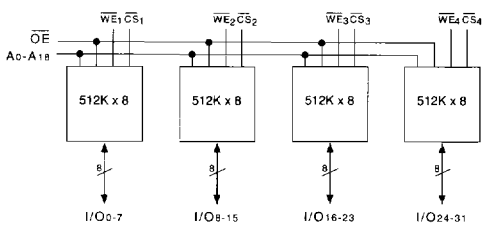
** This data sheet describes a product under development and is subject to change without notice.*

FIG. 1 PIN CONFIGURATION FOR WS512K32N-XHX

TOP VIEW



BLOCK DIAGRAM



PIN DESCRIPTION

I/O0-31	Data Inputs/Outputs
A0-18	Address Inputs
$\overline{WE}_{1-4}$	Write Enables
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

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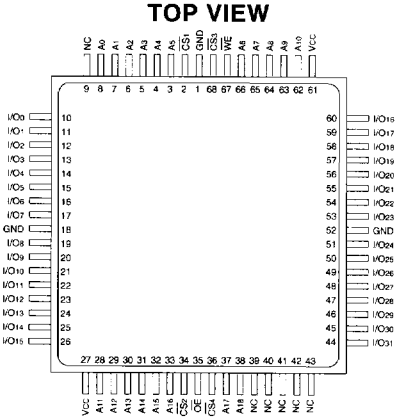
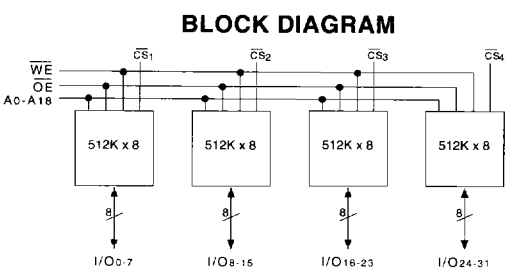
FIG. 2 PIN CONFIGURATION FOR WS512K32-XG4X

TOP VIEW



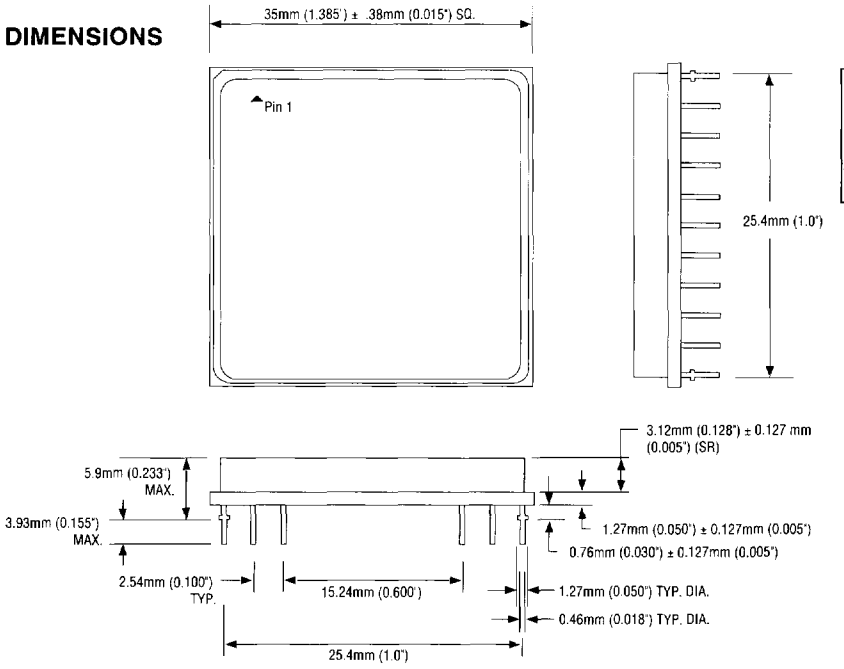
BLOCK DIAGRAM



PIN DESCRIPTION

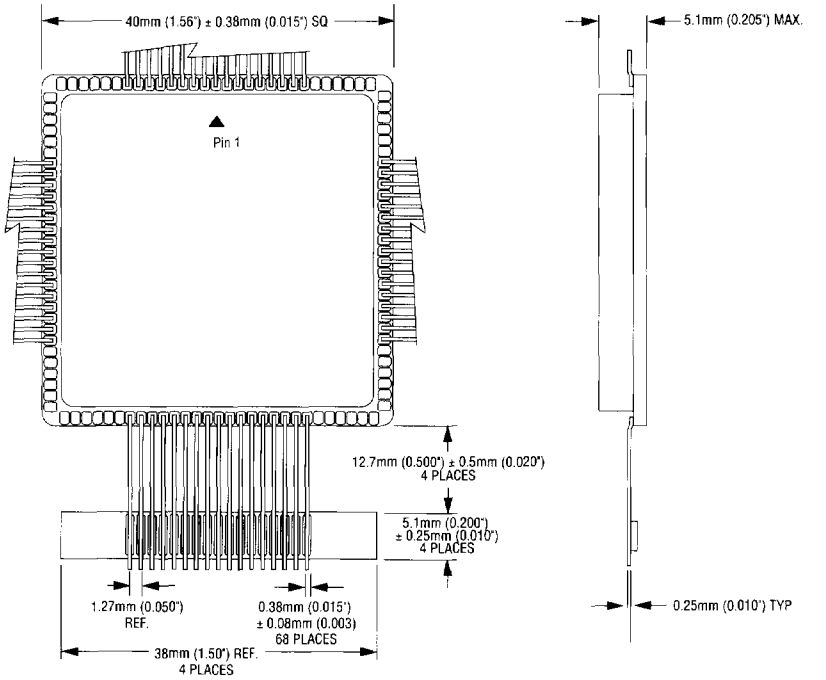
I/O0-31	Data Inputs/Outputs
A0-18	Address Inputs
$\overline{WE}$	Write Enable
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

FIG. 3
PACKAGE DIMENSIONS (16A07)

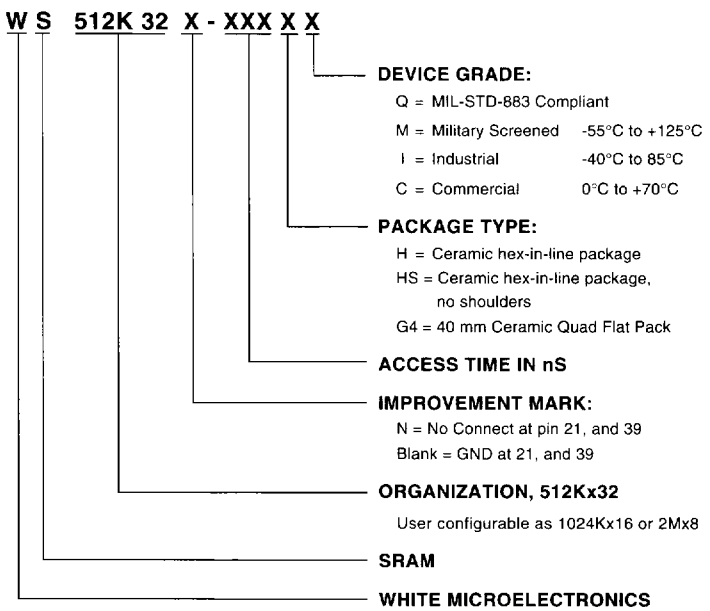


This package is also available without shoulders on the corner pins.

FIG. 4
PACKAGE DIMENSIONS (14A15)



ORDERING INFORMATION



NOTES:

512Kx32 SRAM MODULE *PRELIMINARY**

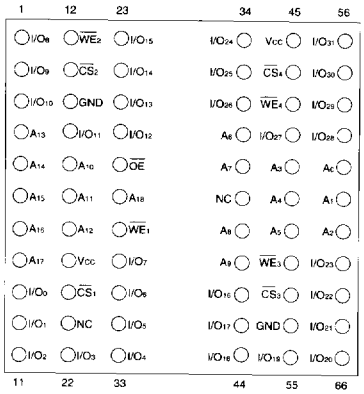
FEATURES

- Access Times of 25nS to 45nS
- Packaging
  - 66-pin, PGA Type, 1.38 inch square HIP, Hermetic Ceramic Package
  - 68 lead, 40 mm Hermetic CQFP Package
- Organized as 512Kx32, User Configurable as 1024Kx16 or 2Mx8.
- Battery Back-Up Operation
- Commercial, Industrial and Military Temperature Ranges
- TTL Compatible Inputs and Outputs
- 3.3 Volt Power Supply
- Low Power CMOS
- Built in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight
  WS512K32-XHX - 13 grams typical
  WS512K32-XG4X - 20 grams typical

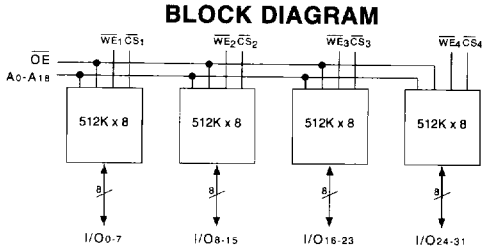
* *This data sheet describes a product under development and is subject to change, without notice.*

FIG. 1 PIN CONFIGURATION FOR WS512K32N-XHX

TOP VIEW



BLOCK DIAGRAM



PIN DESCRIPTION

I/O0-31	Data Inputs/Outputs
A0-18	Address Inputs
$\overline{WE}_{1-4}$	Write Enables
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

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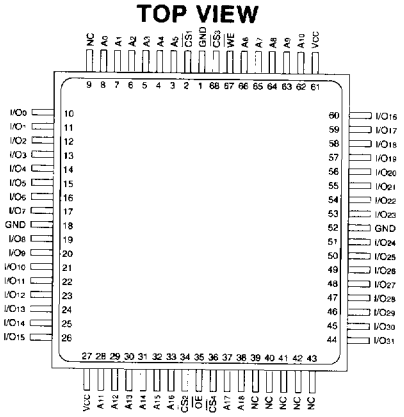
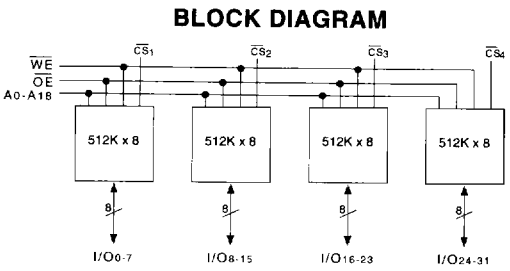
FIG. 2 PIN CONFIGURATION FOR WS512K32-XG4X

TOP VIEW



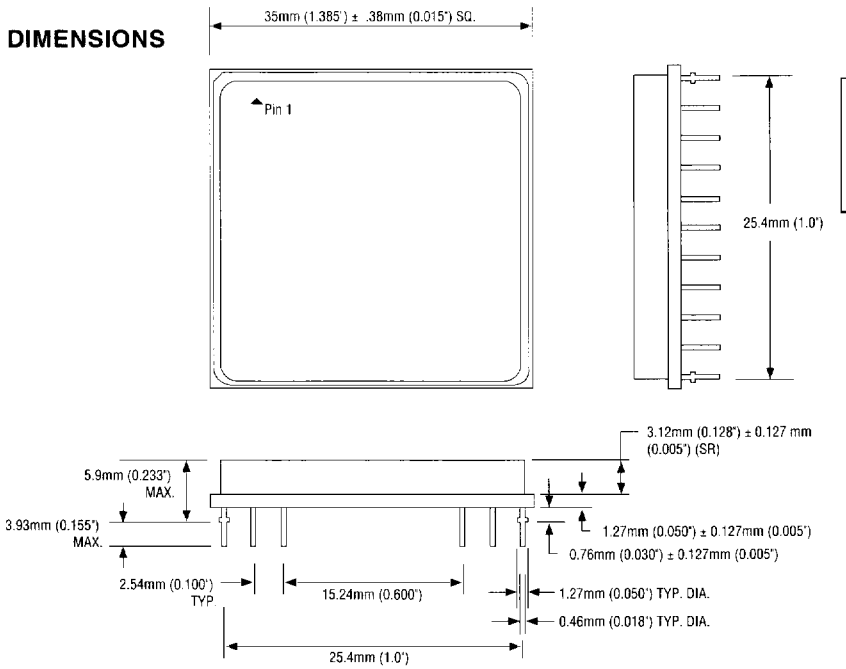
BLOCK DIAGRAM



PIN DESCRIPTION

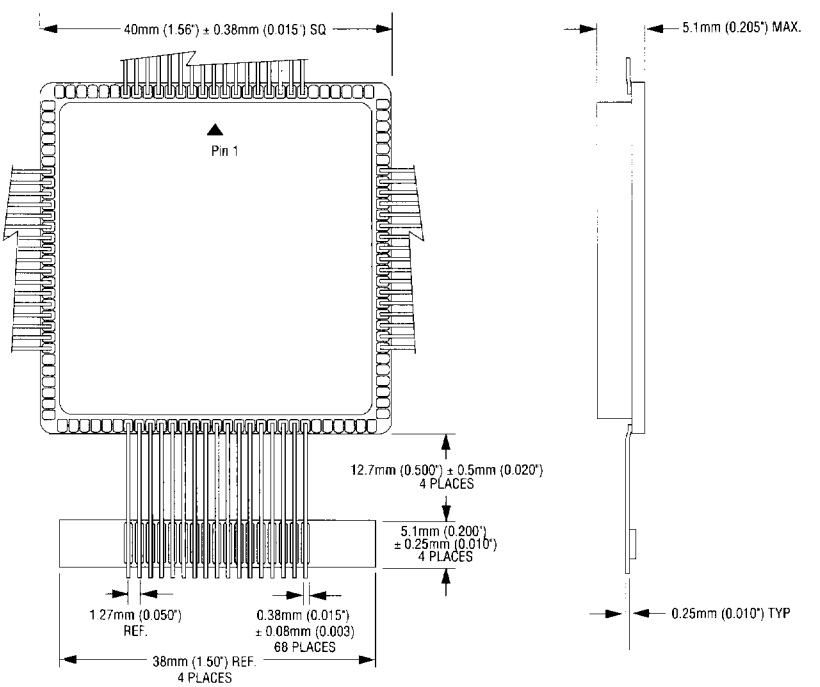
I/O0-31	Data Inputs/Outputs
A0-18	Address Inputs
$\overline{WE}$	Write Enable
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
VCC	Power Supply
GND	Ground
NC	Not Connected

FIG. 3
PACKAGE DIMENSIONS (16A07)



This package is also available without shoulders on the corner pins.

FIG. 4
PACKAGE DIMENSIONS (14A15)



ORDERING INFORMATION